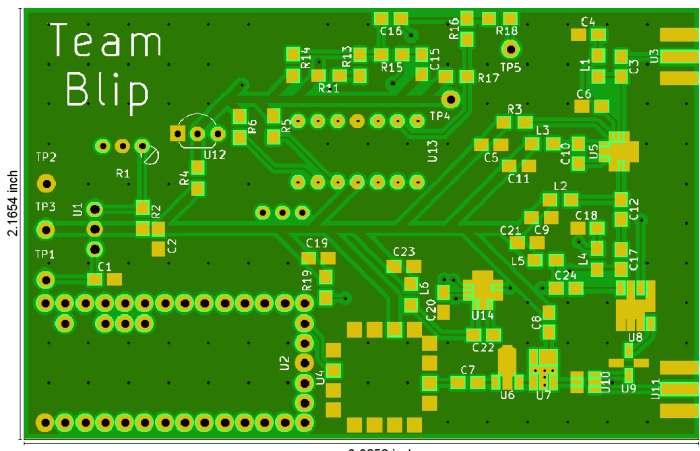
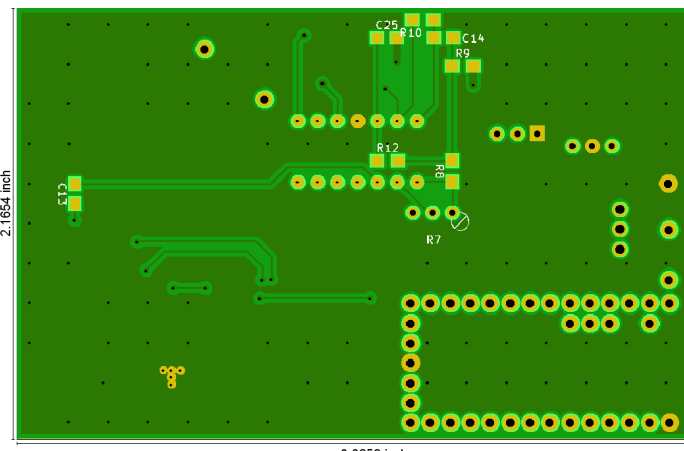


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Single PCB View - Original

Top View	Bottom View
	

Summary - General - Original

PCB Size	3.3858 inch x 2.1654 inch	Copper Layers	2
PCB Thickness	62.00 mil	Solder Mask	Both
Customer Panel Size		Solder Mask Color	Green
SMD Pads Top	177	Legend	Both
SMD Pads Bottom	28	Legend Color	White
SMD Density Top	24 SMD/inch ²	Peeloff Mask	None
SMD Density Bottom	4 SMD/inch ²	Carbon Mask	None
Number of Nets	83	Drill Hole Density	22 Holes/inch ²
Electrical Test	Double Sided	Holes in SMD Pads	Yes
Max. Aspect Ratio on PTH	4.1	Edge Connectors	No
		Surface Finish	

Summary - Copper Layers - Original

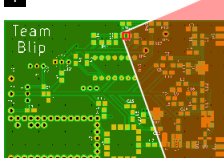
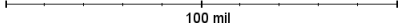
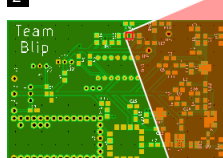
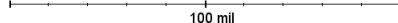
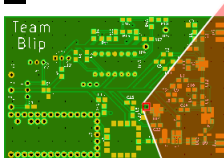
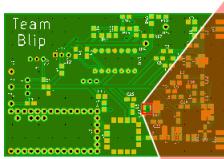

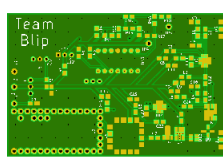
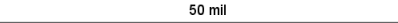
Layer Type	Min. Line Width	Min. Copper Width	Min. Ring	Min. Clr. to Copper	Min. Clr. to Plated Hole	Min. Clr. to NPTH	Min. Clr. to Outline
	mil	mil	mil	mil	mil	mil	mil
Outer	¹ 6.34	² 6.34	³ 7.50	⁴ 6.38	⁵ 13.88	⁶	7.99

Summary - Sequences - Original

Type	Sequences	Tools	Min. End Dia.	Max. End Dia.	Holes	Min. Ring on Outer	Min. Ring on Inner	Min. Clr. Hole to Copper
			mil	mil		mil	mil	mil
Blind	0							
Buried	0							
PTH	1	5	15.00	43.31	162	7.50		13.88
Plated (Total)	1	5	15.00	43.31	162	7.50		13.88
NPTH	0							
Total	1	5	15.00	43.31	162	7.50		13.88

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Summary Minimum Design Characteristics - Locations - Original

<p>1</p>  <p>Team Blip Q2-F.Cu_gbr ⊕ x 3222.91 mil y -1455.55 mil</p> <p>Min. Line Width Outer Layers 6.34 mil</p> 	<p>2</p>  <p>Team Blip Q2-F.Cu_gbr ⊕ x 3222.91 mil y -1455.55 mil</p> <p>Min. Copper Width Outer Layers 6.34 mil</p> 
<p>3</p>  <p>Team Blip Q2-F.Cu_gbr ⊕ x 3531.18 mil y -2585.59 mil</p> <p>Min. Ring Outer Layers 7.50 mil</p> 	<p>4</p>  <p>Team Blip Q2-F.Cu_gbr ⊕ x 3541.61 mil y -2660.2 mil</p> <p>Min. Clearance Outer Layers 6.38 mil</p> 
<p>5</p>  <p>Team Blip Q2-F.Cu_gbr ⊕ x 3541.61 mil y -2663.95 mil</p> <p>Min. Clr. to Plated Outer Layers 13.88 mil</p> 	<p>6</p>  <p>Team Blip Q2-F.Cu_gbr ⊕ x 4759.78 mil y -1574.05 mil</p> <p>Clr. to Outline Outer Layers 7.99 mil</p> 

Stackup - Original



Pressing Stages

1

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Copper Layers - Original

File	Pos.	Min. Line Width	Min. Copper Width	Min. Ring	Min. Clr. to Copper	Min. Same Net spacing	Min. Clr. to Plated Hole	Min. Clr. to NPTH	Min. Clr. to Outline	Copper Area	
		mil	mil	mil	mil	mil	mil	mil	mil	inch ²	%
Q2-F.Cu_gbr	1	6.34	6.34	7.50	6.38	>20.00	13.88		7.99	5.7240	78
Q2-B.Cu_gbr	2	6.34	6.34	7.50	18.16	>20.00	25.66		25.00	6.2909	86

Drill Tools - Original

File	Tool Nr.	Span	Type	Method	FilledVia	Countered	Dia.	Tol. Min	Tol. Plus	Holes (in PCB)	Moves (in PCB)	Double Hits (in File)	Predrill Hits (in File)	Min. Ring on Outer	Min. Ring on Inner	Min. Pad Size
							mil	mil	mil					mil	mil	mil
Q2_drl	2	1-2	PTH	unknown	unknown	unknown	15.00	0.00	0.00	106	0	0	0	7.50		30.00
Q2_drl	3	1-2	PTH	unknown	unknown	unknown	15.75	0.00	0.00	2	0	0	0	9.84		35.43
Q2_drl	4	1-2	PTH	unknown	unknown	unknown	31.50	0.00	0.00	9	0	0	0	12.60		56.70
Q2_drl	5	1-2	PTH	unknown	unknown	unknown	39.37	0.00	0.00	42	0	0	0	19.68		78.73
Q2_drl	6	1-2	PTH	unknown	unknown	unknown	43.31	0.00	0.00	3	0	0	0	11.81		66.93

Sequences - Original

Span	Type	Tools	Min. End Dia.	Max. End Dia.	Holes	Min. Ring on Outer	Min. Ring on Inner	Min. Ring on Outer NPTH	Min. Ring on Inner NPTH	Min. Clr. Hole to Copper	Min. Clr. Hole to Outline	Min. Clr. Slot to Outline
			mil	mil		mil	mil	mil	mil	mil	mil	mil
1-2	PTH	5	15.00	43.31	162	7.50				13.88	56.28	disabled
All	Plated	5	15.00	43.31	162	7.50				13.88	56.28	disabled
All	All	5	15.00	43.31	162	7.50				13.88	56.28	disabled

Rout Tools - Original

File	Tool Nr.	Type	Tool Dia.	End Dia.	Draw Length	Nibble Count
			mil	mil	mil	
Q2_drl	1	PTH	unknown	9.84	112.99	129

Routed Holes - Original

File	Hole Nr.	Instances	X Size	Y Size	Draw Length	Nibble Count
			mil	mil	mil	
Q2_drl	1	2	17.87	9.84	8.03	9
Q2_drl	2	2	17.95	9.84	8.11	9
Q2_drl	3	10	17.91	9.84	8.07	9

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Solder Mask - Original

Side	Min. Ring on Cu Defined Pads	Min. Ring on SM Defined Pads	Min. Clr. Mask to Mask	Min. Web	Min. Clr. Mask to Copper	Fully Covered Via Holes	Partly Covered Via Holes
	mil	mil	mil	mil	mil		
Top	7.87		5.51	1.25	1.27	Yes	No
Bottom	7.87		5.51	>10.00	9.04	Yes	No

Files - Original

Initial	Renamed	Format	Function	Position	Color
Q2-F.SilkS.gbr	Q2-F.SilkS_gbr	ger274x	silk	top	white
Q2-F.Mask.gbr	Q2-F.Mask_gbr	ger274x	mask	top	green
Q2-F.Cu.gbr	Q2-F.Cu_gbr	ger274x	outer	1	
Q2-B.Cu.gbr	Q2-B.Cu_gbr	ger274x	outer	2	
Q2-B.Mask.gbr	Q2-B.Mask_gbr	ger274x	mask	bottom	green
Q2-B.SilkS.gbr	Q2-B.SilkS_gbr	ger274x	silk	bottom	white
Q2.drl	Q2_drl	excellon2	plated	1-2	
Q2-Edge.Cuts.gbr	Q2-Edge.Cuts_gbr	ger274x	cad_outline	none	

Input Remarks - Original

Gerber import: Invalid coincident draw, continuing without cleanup 'Q2-B.Cu.gbr'
Gerber import: Self-intersecting contours are detected, continuing with an interpretation of the contours. 'Q2-B.Cu.gbr' (at line 1419)
Gerber import: Self-intersecting contours are detected, continuing with an interpretation of the contours. 'Q2-F.Cu.gbr' (at line 3440)

Comments - Original

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